Program: TEC-4MOD or TEC-6MOD

Part Orientation:

1. Pitch Adapter to Silicon Bonds

Lead Reference System (L): Pitch Adapter

Die Reference System (U): Silicon

First Bond: Pitch Adapter
Bond time: 20 ms
USG Current: 60 to 75mA
Force: 20

Loop Parameters:
Shape: square
Loop height: 50 mils
Clear height: 60 mils
clamp close at loop

Second Bond: Silicon
Bond time: 20 ms
USG Current: 45 to 55mA
Force: 35

Tail Parameters:
Feed: 75
2. Silicon to Silicon Bonds

**Lead Reference System (L): Left Silicon wafer**

First Bond: Left Silicon wafer
- Bond time: 20 ms
- USG Current: 45 to 50mA
- Force: 35

**Loop Parameters:**
- Shape: square
- Loop height: 50 mils
- Clear height: 60 mils
- Clamp close at loop

**Die Reference System (U): Right Silicon wafer**

Second Bond: Right Silicon wafer
- Bond time: 20 ms
- USG Current: 45 to 55mA
- Force: 35

**Tail Parameters:**
- Feed: 75
3. Bias Bonds

**Bond Locations:**

First Bond: Pitch Adapter  
Second Bond: Silicon

**Bond time:** 20 ms  
**USG Current:** 60 to 75mA  
**Force:** 20

Bond foot at wire angle

**Loop Parameters:**

- **Shape:** square
- **Loop height:** 45 mils
- **Clamp close at loop**

**Second Bond: Silicon**

- **Bond time:** 20 ms
- **USG Current:** 45 to 50mA
- **Force:** 35

**Tail Parameters:**

- **Feed:** 75
Silicon to Silicon:

**First Bond: Left Silicon wafer**
- Bond time: 20 ms
- USG Current: 45 to 55mA
- Force: 35

**Loop Parameters:**
- Shape: square
- Loop height: 45 mils
- Clamp close at loop

**Second Bond: Right Silicon wafer**
- Bond time: 20 ms
- USG Current: 45 to 55mA
- Force: 35

**Tail Parameters:**
- Feed: 75